

FIGS. 20D are top plan views of upper sides of wafer guides showing various embodiments of the invention.

FIGS. 21A is a front views of the wafer guide of FIG. 20A.

FIGS. 21B is a front views of the wafer guides of FIG. 20B.

FIGS. 21C is a front views of the wafer guides of FIG. 20C.

FIGS. 21D is a front views of the wafer guides of FIG. 20D.

FIGS. 22A is a side views of the wafer guide of FIGS. 20A and 21A.

B1

FIGS. 22B is a side views of the wafer guide of FIGS. 20B and 21B.

FIGS. 22C is a side views of the wafer guide of FIGS. 20C and 21C.

FIGS. 22D is a side views of the wafer guide of FIGS. 20D and 21D.

FIGS. 23A is a cross-sectional view from above through an H-bar wafer carrier showing the wafer support at an insertion retraction position.

FIGS. 23B is a cross-sectional view from above through an H-bar wafer carrier showing the wafer support at an insertion retraction position.

FIGS. 23C is a cross-sectional view from above through an H-bar wafer carrier showing the wafer support at an insertion retraction position.

FIGS. 23D is a cross-sectional view from above through an H-bar wafer carrier showing the wafer support at an insertion retraction position.